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Details	
Product Status	Active
Number of LABs/CLBs	3491
Number of Logic Elements/Cells	55856
Total RAM Bits	2396160
Number of I/O	324
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce55f23c6

2. Logic Elements and Logic Array Blocks in Cyclone IV Devices

CYIV-51002-1.0

This chapter contains feature definitions for logic elements (LEs) and logic array blocks (LABs). Details are provided on how LEs work, how LABs contain groups of LEs, and how LABs interface with the other blocks in Cyclone® IV devices.

Logic Elements

Logic elements (LEs) are the smallest units of logic in the Cyclone IV device architecture. LEs are compact and provide advanced features with efficient logic usage. Each LE has the following features:

- A four-input look-up table (LUT), which can implement any function of four variables
- A programmable register
- A carry chain connection
- A register chain connection
- The ability to drive the following interconnects:
  - Local
  - Row
  - Column
  - Register chain
  - Direct link
- Register packing support
- Register feedback support

Clocking Modes

Cyclone IV devices M9K memory blocks support the following clocking modes:

- Independent
- Input or output
- Read or write
- Single-clock

When using read or write clock mode, if you perform a simultaneous read or write to the same address location, the output read data is unknown. If you require the output data to be a known value, use either single-clock mode or I/O clock mode and choose the appropriate read-during-write behavior in the MegaWizard Plug-In Manager.

Violating the setup or hold time on the memory block input registers might corrupt the memory contents. This applies to both read and write operations.

Asynchronous clears are available on read address registers, output registers, and output latches only.

Table 3–5 lists the clocking mode versus memory mode support matrix.

Table 3–5. Cyclone IV Devices Memory Clock Modes

Clocking Mode	True Dual-Port Mode	Simple Dual-Port Mode	Single-Port Mode	ROM Mode	FIFO Mode
Independent	✓	—	—	✓	—
Input or output	✓	✓	✓	✓	—
Read or write	—	✓	—	—	✓
Single-clock	✓	✓	✓	✓	✓

Independent Clock Mode

Cyclone IV devices M9K memory blocks can implement independent clock mode for true dual-port memories. In this mode, a separate clock is available for each port (port A and port B). `clock A` controls all registers on the port A side, while `clock B` controls all registers on the port B side. Each port also supports independent clock enables for port A and B registers.

Input or Output Clock Mode

Cyclone IV devices M9K memory blocks can implement input or output clock mode for FIFO, single-port, true, and simple dual-port memories. In this mode, an input clock controls all input registers to the memory block including data, address, `byteena`, `wren`, and `rden` registers. An output clock controls the data-output registers. Each memory block port also supports independent clock enables for input and output registers.

Table 5–2. GCLK Network Connections for EP4CGX30, EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 Devices (1), (2) (Part 4 of 4)

GCLK Network Clock Sources	GCLK Networks																												
	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29
DPCLK17	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	✓	—	—	—	—	—	—	—	—	—	—

Notes to Table 5–2:

(1) EP4CGX30 information in this table refers to only EP4CGX30 device in F484 package.

(2) PLL_1, PLL_2, PLL_3, and PLL_4 are general purpose PLLs while PLL_5, PLL_6, PLL_7, and PLL_8 are multipurpose PLLs.

(3) PLL_7 and PLL_8 are not available in EP4CXGX30, EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 devices in F484 package.

Table 5–3. GCLK Network Connections for Cyclone IV E Devices (1) (Part 1 of 3)

GCLK Network Clock Sources	GCLK Networks																			
	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19
CLK1	—	✓	✓	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
CLK2/DIFFCLK_1p	—	✓	—	✓	✓	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
CLK3/DIFFCLK_1n	✓	—	—	✓	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
CLK4/DIFFCLK_2p	—	—	—	—	—	✓	—	✓	—	✓	—	—	—	—	—	—	—	—	—	—
CLK5/DIFFCLK_2n	—	—	—	—	—	—	✓	✓	—	—	—	—	—	—	—	—	—	—	—	—
CLK6/DIFFCLK_3p	—	—	—	—	—	—	✓	—	✓	✓	—	—	—	—	—	—	—	—	—	—
CLK7/DIFFCLK_3n	—	—	—	—	—	✓	—	—	✓	—	—	—	—	—	—	—	—	—	—	—
CLK8/DIFFCLK_5n (2)	—	—	—	—	—	—	—	—	—	—	✓	—	✓	—	✓	—	—	—	—	—
CLK9/DIFFCLK_5p (2)	—	—	—	—	—	—	—	—	—	—	—	✓	✓	—	—	—	—	—	—	—
CLK10/DIFFCLK_4n (2)	—	—	—	—	—	—	—	—	—	—	—	✓	—	✓	✓	—	—	—	—	—
CLK11/DIFFCLK_4p (2)	—	—	—	—	—	—	—	—	—	—	✓	—	—	✓	—	—	—	—	—	—
CLK12/DIFFCLK_7n (2)	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	✓	—	✓	—	✓
CLK13/DIFFCLK_7p (2)	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	✓	✓	—	—
CLK14/DIFFCLK_6n (2)	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	✓	—	✓	✓

Designing with LVDS

Cyclone IV I/O banks support the LVDS I/O standard. The Cyclone IV GX right I/O banks support true LVDS transmitters while the Cyclone IV E left and right I/O banks support true LVDS transmitters. On the top and bottom I/O banks, the emulated LVDS transmitters are supported using two single-ended output buffers with external resistors. One of the single-ended output buffers is programmed to have opposite polarity. The LVDS receiver requires an external 100-Ω termination resistor between the two signals at the input buffer.

Figure 6–12 shows a point-to-point LVDS interface using Cyclone IV devices true LVDS output and input buffers.

Figure 6–12. Cyclone IV Devices LVDS Interface with True Output Buffer on the Right I/O Banks

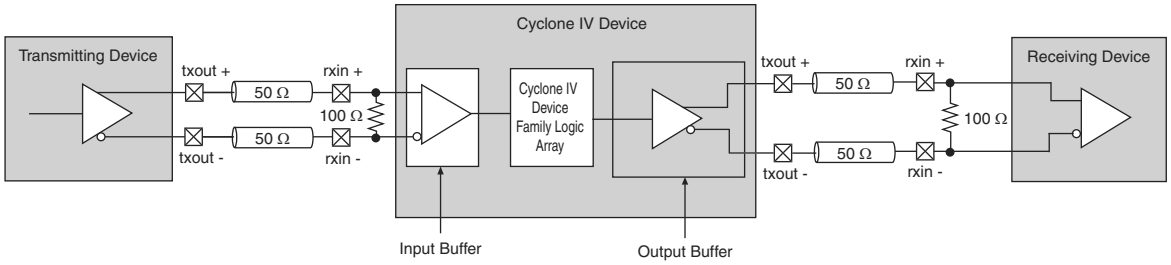
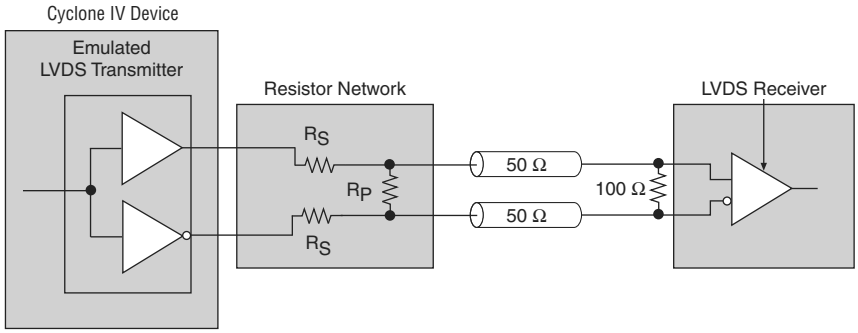


Figure 6–13 shows a point-to-point LVDS interface with Cyclone IV devices LVDS using two single-ended output buffers and external resistors.

Figure 6–13. LVDS Interface with External Resistor Network on the Top and Bottom I/O Banks *(1)*



Note to Figure 6–13:

(1) R_S = 120 Ω. R_P = 170 Ω.

BLVDS I/O Standard Support in Cyclone IV Devices

The BLVDS I/O standard is a high-speed differential data transmission technology that extends the benefits of standard point-to-point LVDS to multipoint configuration that supports bidirectional half-duplex communication. BLVDS differs from standard LVDS by providing a higher drive to achieve similar signal swings at the receiver while loaded with two terminations at both ends of the bus.

8. Configuration and Remote System Upgrades in Cyclone IV Devices

CYIV-51008-1.7

This chapter describes the configuration and remote system upgrades in Cyclone® IV devices. Cyclone IV (Cyclone IV GX and Cyclone IV E) devices use SRAM cells to store configuration data. You must download the configuration data to Cyclone IV devices each time the device powers up because SRAM memory is volatile.

Cyclone IV devices are configured using one of the following configuration schemes:

- Active serial (AS)
- Active parallel (AP) (supported in Cyclone IV E devices only)
- Passive serial (PS)
- Fast passive parallel (FPP) (not supported in EP4CGX15, EP4CGX22, and EP4CGX30 [except for the F484 package] devices)
- JTAG

Cyclone IV devices offer the following configuration features:

- Configuration data decompression (“Configuration Data Decompression” on page 8–2)
- Remote system upgrade (“Remote System Upgrade” on page 8–69)

System designers face difficult challenges, such as shortened design cycles, evolving standards, and system deployments in remote locations. Cyclone IV devices help overcome these challenges with inherent re-programmability and dedicated circuitry to perform remote system upgrades. Remote system upgrades help deliver feature enhancements and bug fixes without costly recalls, reduced time-to-market, and extended product life.

Configuration

This section describes Cyclone IV device configuration and includes the following topics:

Configuration Scheme

A configuration scheme with different configuration voltage standards is selected by driving the MSEL pins either high or low, as shown in Table 8–3, Table 8–4, and Table 8–5.

☞ Hardwire the MSEL pins to V_{CCA} or GND without pull-up or pull-down resistors to avoid problems detecting an incorrect configuration scheme. Do not drive the MSEL pins with a microprocessor or another device.

Table 8–3. Configuration Schemes for Cyclone IV GX Devices (EP4CGX15, EP4CGX22, and EP4CGX30 [except for F484 Package])

Configuration Scheme	MSEL2	MSEL1	MSEL0	POR Delay	Configuration Voltage Standard (V) (1)
AS	1	0	1	Fast	3.3
	0	1	1	Fast	3.0, 2.5
	0	0	1	Standard	3.3
	0	1	0	Standard	3.0, 2.5
PS	1	0	0	Fast	3.3, 3.0, 2.5
	1	1	0	Fast	1.8, 1.5
	0	0	0	Standard	3.3, 3.0, 2.5
JTAG-based configuration (2)	(3)	(3)	(3)	—	—

Notes to Table 8–3:

(1) Configuration voltage standard applied to the V_{CCIO} supply of the bank in which the configuration pins reside.

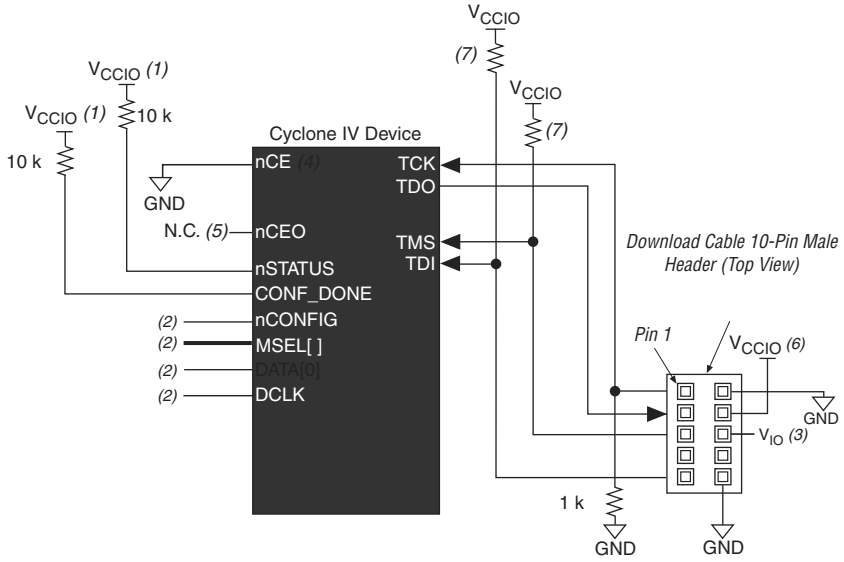
(2) JTAG-based configuration takes precedence over other configuration schemes, which means the MSEL pin settings are ignored.

(3) Do not leave the MSEL pins floating. Connect them to V_{CCA} or GND. These pins support the non-JTAG configuration scheme used in production. Altera recommends connecting the MSEL pins to GND if your device is only using JTAG configuration.

Table 8–4. Configuration Schemes for Cyclone IV GX Devices (EP4CGX30 [only for F484 package], EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150) (Part 1 of 2)

Configuration Scheme	MSEL3	MSEL2	MSEL1	MSEL0	POR Delay	Configuration Voltage Standard (V) (1)
AS	1	1	0	1	Fast	3.3
	1	0	1	1	Fast	3.0, 2.5
	1	0	0	1	Standard	3.3
	1	0	1	0	Standard	3.0, 2.5
PS	1	1	0	0	Fast	3.3, 3.0, 2.5
	1	1	1	0	Fast	1.8, 1.5
	1	0	0	0	Standard	3.3, 3.0, 2.5
	0	0	0	0	Standard	1.8, 1.5
FPP	0	0	1	1	Fast	3.3, 3.0, 2.5
	0	1	0	0	Fast	1.8, 1.5
	0	0	0	1	Standard	3.3, 3.0, 2.5
	0	0	1	0	Standard	1.8, 1.5

Figure 8–24. JTAG Configuration of a Single Device Using a Download Cable (1.5-V or 1.8-V V_{CCIO} Powering the JTAG Pins)



Notes to Figure 8–24:

(1) Connect these pull-up resistors to the V_{CCIO} supply of the bank in which the pin resides.

(2) Connect the nCONFIG and MSEL pins to support a non-JTAG configuration scheme. If you only use JTAG configuration, connect the nCONFIG pin to logic-high and the MSEL pins to GND. In addition, pull DCLK and DATA[0] to either high or low, whichever is convenient on your board.

(3) In the USB-Blaster and ByteBlaster II cables, this pin is connected to nCE when it is used for AS programming; otherwise it is a no connect.

(4) The nCE must be connected to GND or driven low for successful JTAG configuration.

(5) The nCEO pin is left unconnected or used as a user I/O pin when it does not feed the nCE pin of another device.

(6) Power up the V_{CC} of the EthernetBlaster, ByteBlaster II or USB-Blaster cable with supply from V_{CCIO}. The Ethernet-Blaster, ByteBlaster II, and USB-Blaster cables do not support a target supply voltage of 1.2 V. For the target supply voltage value, refer to the *ByteBlaster II Download Cable User Guide*, the *USB-Blaster Download Cable User Guide*, and the *EthernetBlaster Communications Cable User Guide*.

(7) Resistor value can vary from 1 kΩ to 10 kΩ.

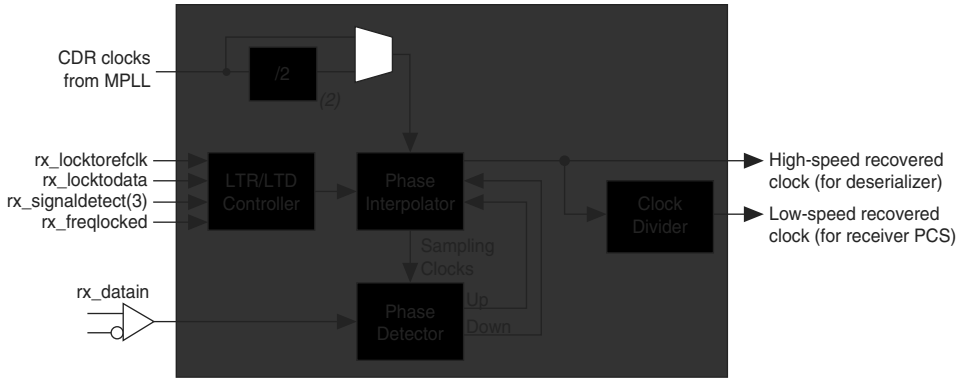
To configure a single device in a JTAG chain, the programming software places all other devices in bypass mode. In bypass mode, devices pass programming data from the TDI pin to the TDO pin through a single bypass register without being affected internally. This scheme enables the programming software to program or verify the target device. Configuration data driven into the device appears on the TDO pin one clock cycle later.

The Quartus II software verifies successful JTAG configuration after completion. At the end of configuration, the software checks the state of CONF_DONE through the JTAG port. When Quartus II generates a **.jam** for a multi-device chain, it contains instructions so that all the devices in the chain are initialized at the same time. If CONF_DONE is not high, the Quartus II software indicates that configuration has failed. If CONF_DONE is high, the software indicates that configuration was successful. After the configuration bitstream is serially sent using the JTAG TDI port, the TCK port clocks an additional clock cycles to perform device initialization.

Clock Data Recovery

Each receiver channel has an independent CDR unit to recover the clock from the incoming serial data stream. The high-speed recovered clock is used to clock the deserializer for serial-to-parallel conversion of the received input data, and low-speed recovered clock to clock the receiver PCS blocks. Figure 1–15 illustrates the CDR unit block diagram.

Figure 1–15. CDR Unit Block Diagram



Notes to Figure 1–15:

(1) Optional RX local divider for CDR clocks from multipurpose PLL is only available in each CDR unit for EP4CGX30 (F484 package), EP4CGX50, and EP4CGX75 devices. This block is used with the transceiver dynamic reconfiguration feature. For more information, refer to the *Cyclone IV Dynamic Reconfiguration* chapter and *AN 609: Implementing Dynamic Reconfiguration in Cyclone IV GX Devices*.

(2) CDR state transition in automatic lock mode is not dependent on `rx_signaldetect` signal, except when configured in PCI Express (PIPE) mode only.

Each CDR unit gets the reference clock from one of the two multipurpose phase-locked loops (PLLs) adjacent to the transceiver block. The CDR works by tracking the incoming data with a phase detector and finding the optimum sampling clock phase from the phase interpolator unit. The CDR operations are controlled by the LTR/LTD controller block, where the CDR may operate in the following states:

- Lock-to-reference (LTR) state—phase detector disabled and CDR ignores incoming data
- Lock-to-data (LTD) state—phase detector enabled and CDR tracks incoming data to find the optimum sampling clock phase

State transitions are supported with automatic lock mode and manual lock mode.

Automatic Lock Mode

Upon receiver power-up and reset cycle, the CDR is put into LTR state. Transition to the LTD state is performed automatically when both of the following conditions are met:

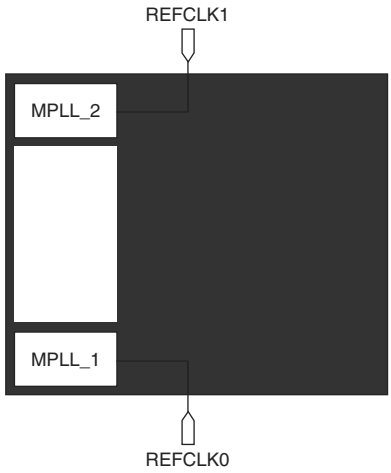
- Signal detection circuitry indicates the presence of valid signal levels at the receiver input buffer. This condition is valid for PCI Express (PIPE) mode only. CDR transitions are not dependent on signal detection circuitry in other modes.
- The recovered clock is within the configured part per million (ppm) frequency threshold setting with respect to the CDR clocks from multipurpose PLL.

Input Reference Clocking

When used for transceiver, the left PLLs synthesize the input reference clock to generate the required clocks for the transceiver channels. Figure 1–25 and Figure 1–26 show the sources of input reference clocks for PLLs used in the transceiver operation.

☞ Clock output from PLLs in the FPGA core cannot feed into PLLs used by the transceiver as input reference clock.

Figure 1–25. PLL Input Reference Clocks in Transceiver Operation for F324 and Smaller Packages (1), (2)



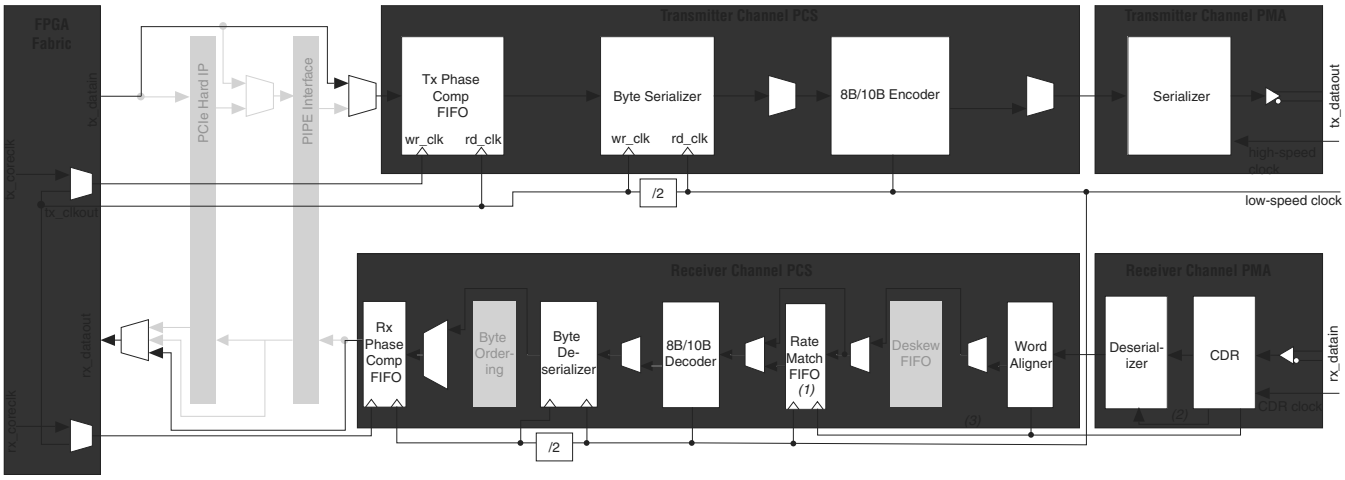
Notes to Figure 1–25:

(1) The REFCLK0 and REFCLK1 pins are dual-purpose CLK, REFCLK, or DIFFCLK pins that reside in banks 3A and 8A respectively.

(2) Using any clock input pins other than the designated REFCLK pins as shown here to drive the MPLLs may have reduced jitter performance.

Figure 1–60 shows the transceiver channel datapath and clocking when configured in Serial RapidIO mode.

Figure 1–60. Transceiver Channel Datapath and Clocking when Configured in Serial RapidIO Mode



Notes to Figure 1–60:

(1) Optional rate match FIFO.

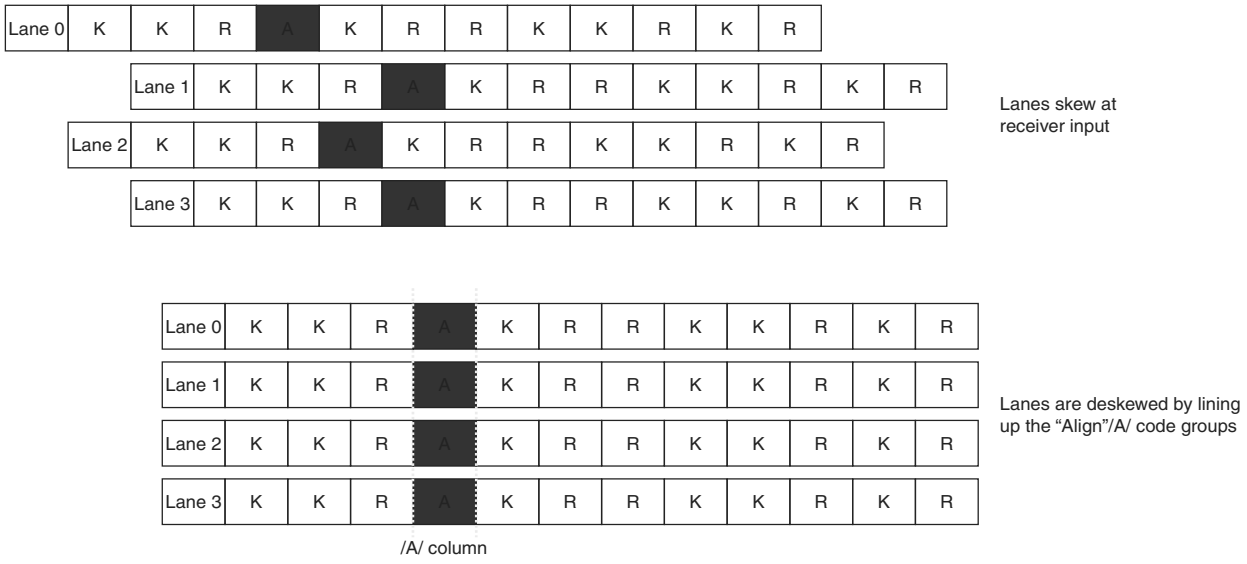
(2) High-speed recovered clock.

(3) Low-speed recovered clock.

- Channel alignment is acquired if three additional aligned ||A|| columns are observed at the output of the deskew FIFOs of the four channels after alignment of the first ||A|| column.
- Channel alignment is indicated by the assertion of `rx_channelaligned` signal.
- After acquiring channel alignment, if four misaligned ||A|| columns are seen at the output of the deskew FIFOs in all four channels with no aligned ||A|| columns in between, the `rx_channelaligned` signal is deasserted, indicating loss of channel alignment.

Figure 1–65 shows lane skew at the receiver input and how the deskew FIFO uses the /A/ code group to align the channels.

Figure 1–65. Deskew FIFO–Lane Skew at the Receiver Input



Lane Synchronization

In XAUI mode, the word aligner is configured in automatic synchronization state machine mode that is compliant to the PCS synchronization state diagram specified in clause 48 of the IEEE P802.3ae specification. Table 1–23 lists the synchronization state machine parameters that implements the lane synchronization in XAUI mode.

Table 1–23. Synchronization State Machine Parameters (1)

Parameter	Value
Number of valid synchronization (/K28.5/) code groups received to achieve synchronization	4
Number of erroneous code groups received to lose synchronization	4
Number of continuous good code groups received to reduce the error count by one	4

Note to Table 1–23:

(1) The word aligner supports 7-bit and 10-bit pattern lengths in XAUI mode.

Document Revision History

Table 1–30 lists the revision history for this chapter.

Table 1–30. Document Revision History

Date	Version	Changes
February 2015	3.7	■ Updated the GiGE row in Table 1–14. ■ Updated the "GIGE Mode" section. ■ Updated the note in the "Clock Frequency Compensation" section.
October 2013	3.6	Updated Figure 1–15 and Table 1–4.
May 2013	3.5	Updated Table 1–27 by setting "rx_locktodata" and "rx_locktorefclk" to "Input"
October 2012	3.4	■ Updated the data rate for the V-by-one protocol and the F324 package support in HD-SDI in Table 1–1. ■ Updated note (1) to Figure 1–27. ■ Added latency information to Figure 1–67.
November 2011	3.3	■ Updated "Word Aligner" and "Basic Mode" sections. ■ Updated Figure 1–37.
December 2010	3.2	■ Updated for the Quartus II software version 10.1 release. ■ Updated Table 1–1, Table 1–5, Table 1–11, Table 1–14, Table 1–24, Table 1–25, Table 1–26, Table 1–27, Table 1–28, and Table 1–29. ■ Updated "8B/10B Encoder", "Transmitter Output Buffer", "Receiver Input Buffer", "Clock Data Recovery", "Miscellaneous Transmitter PCS Features", "Miscellaneous Receiver PCS Feature", "Input Reference Clocking", "PCI Express (PIPE) Mode", "Channel Deskewing", "Lane Synchronization", "Serial Loopback", and "Self Test Modes" sections. ■ Added Figure 1–9, Figure 1–10, Figure 1–19, Figure 1–20, and Figure 1–43. ■ Updated Figure 1–53, Figure 1–55, Figure 1–59, Figure 1–60, Figure 1–69, Figure 1–70, Figure 1–71, Figure 1–72, Figure 1–73, and Figure 1–74.
November 2010	3.1	Updated Introductory information.
July 2010	3.0	■ Updated information for the Quartus II software version 10.0 release. ■ Reset control, power down, and dynamic reconfiguration information moved to new *Cyclone IV Reset Control and Power Down* and *Cyclone IV Dynamic Reconfiguration* chapters.

Read Transaction

If you want to read the existing values from a specific channel connected to the ALTGX_RECONFIG instance, observe the corresponding byte positions of the PMA control output port after the read transaction is completed.

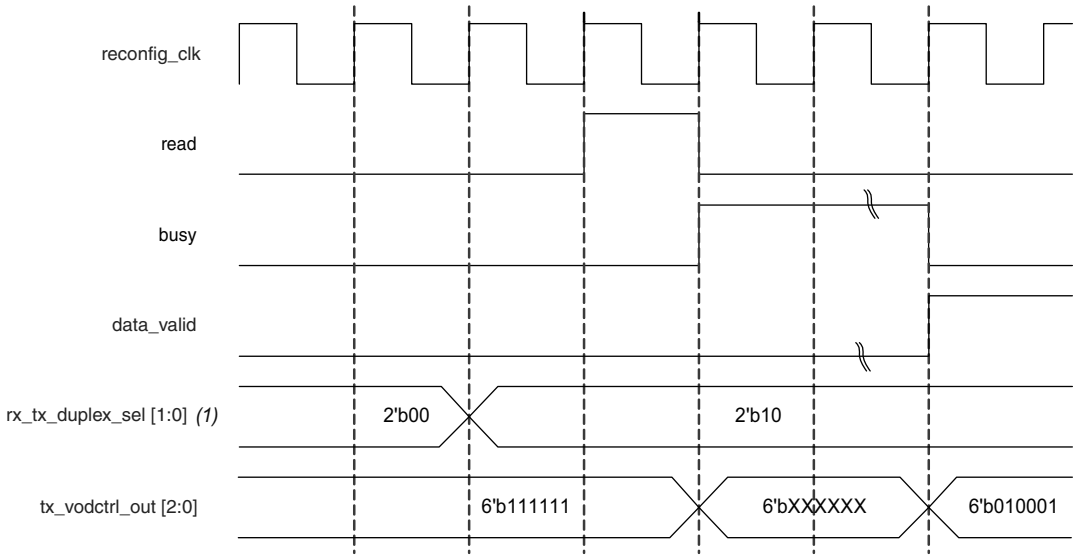
For example, if the number of channels controlled by the ALTGX_RECONFIG is two, the `tx_vodctrl_out` is 6 bits wide. The `tx_vodctrl_out[2:0]` signal corresponds to channel 1 and the `tx_vodctrl_out[5:3]` signal corresponds to channel 2.

To complete a read transaction to the V_{OD} values of the second channel, perform the following steps:

1. Before you initiate a read transaction, set the `rx_tx_duplex_sel` port to **2'b10** so that only the transmit PMA controls are read from the transceiver channel.
2. Ensure that the `busy` signal is low before you start a read transaction.
3. Assert the read signal for one `reconfig_clk` clock cycle. This initiates the read transaction.
4. The `busy` output status signal is asserted high to indicate that the dynamic reconfiguration controller is busy reading the PMA control settings.
5. When the read transaction has completed, the `busy` signal goes low. The `data_valid` signal is asserted, indicating that the data available at the read control signal is valid.
6. To read the current V_{OD} values in channel 2, observe the values in `tx_vodctrl_out[5:3]`.

In the waveform example shown in Figure 3–7, the transmit V_{OD} settings written in channels 1 and 2 prior to the read transaction are 3'b001 and 3'b010, respectively.

Figure 3–7. Read Transaction Waveform—Use the same control signal for all the channels Option Enabled



Note to Figure 3–7:

(1) In this waveform example, you want to read from only the transmitter portion of all the channels.

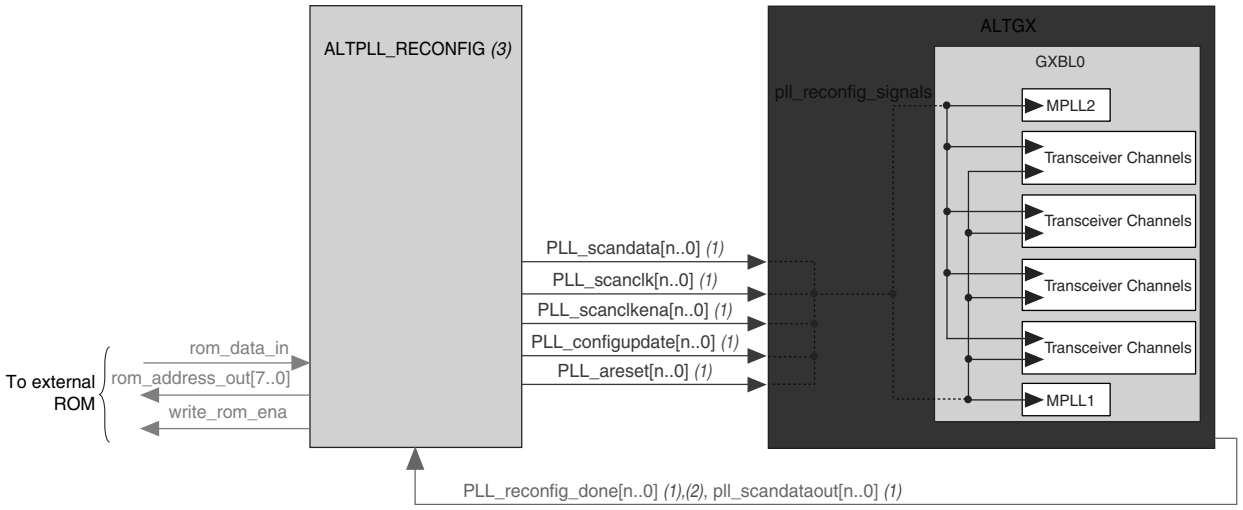
☞ Simultaneous write and read transactions are not allowed.

The .**mif** files carries the reconfiguration information that will be used to reconfigure the multipurpose PLL or general purpose PLL dynamically. The .**mif** contents is generated automatically when you select the **Enable PLL Reconfiguration** option in the **Reconfiguration Setting** in ALTGX instances. The **.mif** files will be generated based on the data rate and input reference clock setting in the ALTGX MegaWizard. You must use the external ROM and feed its content to the ALTPLL_RECONFIG megafunction to reconfigure the multipurpose PLL setting.

For more information about instantiating the ALTPLL_Reconfig, refer to the *AN 609: Implementing Dynamic Reconfiguration in Cyclone IV GX Devices*.

Figure 3–16 shows the connection for PLL reconfiguration mode.

Figure 3–16. ALTGX and ALTPLL_RECONFIG Connection for PLL Reconfiguration Mode



Notes to Figure 3–16:

(1) *<n>* = (number of transceiver PLLs configured in the ALTGX MegaWizard) - 1.

(2) You must connect the `pll_reconfig_done` signal from the ALTGX to the `pll_scandone` port from ALTPLL_RECONFIG.

(3) You need two ALTPLL_RECONFIG controllers if you have two separate ALTGX instances with transceiver PLL instantiated in each ALTGX instance.

For more information about connecting the ALTPLL_RECONFIG and ALTGX instances, refer to the *AN 609: Implementing Dynamic Reconfiguration in Cyclone IV GX Devices*.

Contents

Recommended Operating Conditions

This section lists the functional operation limits for AC and DC parameters for Cyclone IV devices. Table 1–3 and Table 1–4 list the steady-state voltage and current values expected from Cyclone IV E and Cyclone IV GX devices. All supplies must be strictly monotonic without plateaus.

Table 1–3. Recommended Operating Conditions for Cyclone IV E Devices (1), (2) (Part 1 of 2)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CCINT} (3)	Supply voltage for internal logic, 1.2-V operation	—	1.15	1.2	1.25	V
	Supply voltage for internal logic, 1.0-V operation	—	0.97	1.0	1.03	V
V_{CCIO} (3), (4)	Supply voltage for output buffers, 3.3-V operation	—	3.135	3.3	3.465	V
	Supply voltage for output buffers, 3.0-V operation	—	2.85	3	3.15	V
	Supply voltage for output buffers, 2.5-V operation	—	2.375	2.5	2.625	V
	Supply voltage for output buffers, 1.8-V operation	—	1.71	1.8	1.89	V
	Supply voltage for output buffers, 1.5-V operation	—	1.425	1.5	1.575	V
	Supply voltage for output buffers, 1.2-V operation	—	1.14	1.2	1.26	V
V_{CCA} (3)	Supply (analog) voltage for PLL regulator	—	2.375	2.5	2.625	V
V_{CCD_PLL} (3)	Supply (digital) voltage for PLL, 1.2-V operation	—	1.15	1.2	1.25	V
	Supply (digital) voltage for PLL, 1.0-V operation	—	0.97	1.0	1.03	V
V_I	Input voltage	—	–0.5	—	3.6	V
V_O	Output voltage	—	0	—	V_{CCIO}	V
T_J	Operating junction temperature	For commercial use	0	—	85	°C
		For industrial use	–40	—	100	°C
		For extended temperature	–40	—	125	°C
		For automotive use	–40	—	125	°C
t_{RAMP}	Power supply ramp time	Standard power-on reset (POR) (5)	50 µs	—	50 ms	—
		Fast POR (6)	50 µs	—	3 ms	—

Table 1–21. Transceiver Specification for Cyclone IV GX Devices (Part 4 of 4)

Symbol/ Description	Conditions	C6			C7, I7			C8			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
PLD-Transceiver Interface											
Interface speed (F324 and smaller package)	—	25	—	125	25	—	125	25	—	125	MHz
Interface speed (F484 and larger package)	—	25	—	156.25	25	—	156.25	25	—	156.25	MHz
Digital reset pulse width	—	Minimum is 2 parallel clock cycles									

Notes to Table 1–21:

(1) This specification is valid for transmitter output jitter specification with a maximum total jitter value of 112 ps, typically for 3.125 Gbps SRIO and XAUI protocols.

(2) The minimum `reconfig_clk` frequency is 2.5 MHz if the transceiver channel is configured in **Transmitter Only** mode. The minimum `reconfig_clk` frequency is 37.5 MHz if the transceiver channel is configured in **Receiver Only** or **Receiver and Transmitter** mode.

(3) The device cannot tolerate prolonged operation at this absolute maximum.

(4) The rate matcher supports only up to ±300 parts per million (ppm).

(5) Supported for the F169 and F324 device packages only.

(6) Supported for the F484, F672, and F896 device packages only. Pending device characterization.

(7) To support CDR ppm tolerance greater than ±300 ppm, implement ppm detector in user logic and configure CDR to Manual Lock Mode.

(8) Asynchronous spread-spectrum clocking is not supported.

(9) For the EP4CGX30 (F484 package only), EP4CGX50, and EP4CGX75 devices, the CDR ppl tolerance is ±200 ppm.

(10) Time taken until `pll_locked` goes high after `pll_powerdown` deasserts.

(11) Time that the CDR must be kept in lock-to-reference mode after `rx_analogreset` deasserts and before `rx_locktodata` is asserted in manual mode.

(12) Time taken to recover valid data after the `rx_locktodata` signal is asserted in manual mode (Figure 1–2), or after `rx_freqlocked` signal goes high in automatic mode (Figure 1–3).

(13) Time taken to recover valid data after the `rx_locktodata` signal is asserted in manual mode.

(14) Time taken to recover valid data after the `rx_freqlocked` signal goes high in automatic mode.

(15) To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.

For more information about the supported maximum clock rate, device and pin planning, IP implementation, and device termination, refer to *Section III: System Performance Specifications* of the *External Memory Interface Handbook*.

Table 1–37 lists the memory output clock jitter specifications for Cyclone IV devices.

Table 1–37. Memory Output Clock Jitter Specifications for Cyclone IV Devices *(1), (2)*

Parameter	Symbol	Min	Max	Unit
Clock period jitter	$t_{JIT(per)}$	–125	125	ps
Cycle-to-cycle period jitter	$t_{JIT(cc)}$	–200	200	ps
Duty cycle jitter	$t_{JIT(duty)}$	–150	150	ps

Notes to Table 1–37:

(1) Memory output clock jitter measurements are for 200 consecutive clock cycles, as specified in the JEDEC DDR2 standard.

(2) The clock jitter specification applies to memory output clock pins generated using DDIO circuits clocked by a PLL output routed on a global clock (GCLK) network.

Duty Cycle Distortion Specifications

Table 1–38 lists the worst case duty cycle distortion for Cyclone IV devices.

Table 1–38. Duty Cycle Distortion on Cyclone IV Devices I/O Pins *(1), (2), (3)*

Symbol	C6		C7, I7		C8, I8L, A7		C9L		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	45	55	%

Notes to Table 1–38:

(1) The duty cycle distortion specification applies to clock outputs from the PLLs, global clock tree, and IOE driving the dedicated and general purpose I/O pins.

(2) Cyclone IV devices meet the specified duty cycle distortion at the maximum output toggle rate for each combination of I/O standard and current strength.

(3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

OCT Calibration Timing Specification

Table 1–39 lists the duration of calibration for series OCT with calibration at device power-up for Cyclone IV devices.

Table 1–39. Timing Specification for Series OCT with Calibration at Device Power-Up for Cyclone IV Devices *(1)*

Symbol	Description	Maximum	Units
t_{OCTCAL}	Duration of series OCT with calibration at device power-up	20	µs

Note to Table 1–39:

(1) OCT calibration takes place after device configuration and before entering user mode.

Table 1–42 and Table 1–43 list the IOE programmable delay for Cyclone IV E 1.2 V core voltage devices.

Table 1–42. IOE Programmable Delay on Column Pins for Cyclone IV E 1.2 V Core Voltage Devices *(1), (2)*

Parameter	Paths Affected	Number of Setting	Min Offset	Max Offset								Unit
				Fast Corner			Slow Corner					
				C6	I7	A7	C6	C7	C8	I7	A7	
Input delay from pin to internal cells	Pad to I/O dataout to core	7	0	1.314	1.211	1.211	2.177	2.340	2.433	2.388	2.508	ns
Input delay from pin to input register	Pad to I/O input register	8	0	1.307	1.203	1.203	2.19	2.387	2.540	2.430	2.545	ns
Delay from output register to output pin	I/O output register to pad	2	0	0.437	0.402	0.402	0.747	0.820	0.880	0.834	0.873	ns
Input delay from dual-purpose clock pin to fan-out destinations	Pad to global clock network	12	0	0.693	0.665	0.665	1.200	1.379	1.532	1.393	1.441	ns

Notes to Table 1–42:

(1) The incremental values for the settings are generally linear. For the exact values for each setting, use the latest version of the Quartus II software.

(2) The minimum and maximum offset timing numbers are in reference to setting **0** as available in the Quartus II software.

Table 1–43. IOE Programmable Delay on Row Pins for Cyclone IV E 1.2 V Core Voltage Devices *(1), (2)*

Parameter	Paths Affected	Number of Setting	Min Offset	Max Offset								Unit
				Fast Corner			Slow Corner					
				C6	I7	A7	C6	C7	C8	I7	A7	
Input delay from pin to internal cells	Pad to I/O dataout to core	7	0	1.314	1.209	1.209	2.201	2.386	2.510	2.429	2.548	ns
Input delay from pin to input register	Pad to I/O input register	8	0	1.312	1.207	1.207	2.202	2.402	2.558	2.447	2.557	ns
Delay from output register to output pin	I/O output register to pad	2	0	0.458	0.419	0.419	0.783	0.861	0.924	0.875	0.915	ns
Input delay from dual-purpose clock pin to fan-out destinations	Pad to global clock network	12	0	0.686	0.657	0.657	1.185	1.360	1.506	1.376	1.422	ns

Notes to Table 1–43:

(1) The incremental values for the settings are generally linear. For the exact values for each setting, use the latest version of the Quartus II software.

(2) The minimum and maximum offset timing numbers are in reference to setting **0** as available in the Quartus II software.